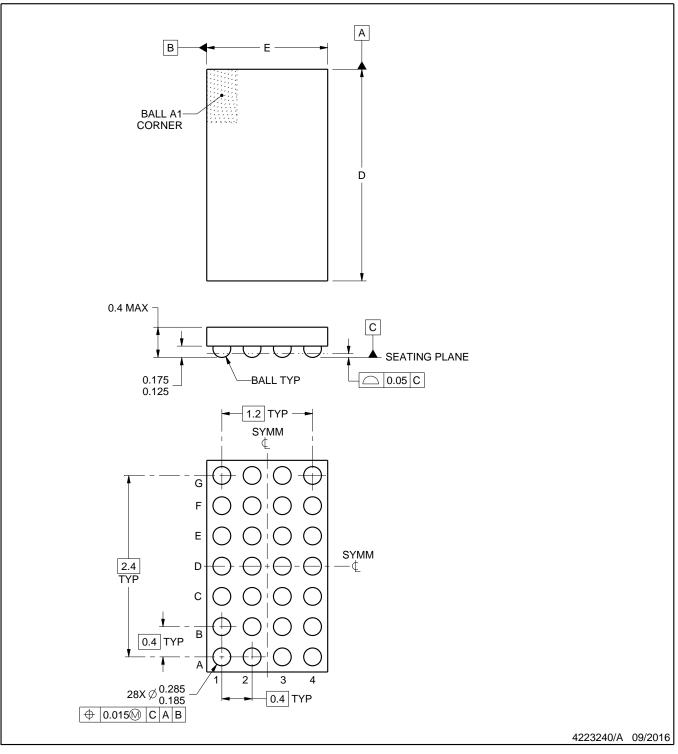
### **YFD0028**



### **PACKAGE OUTLINE**

### DSBGA - 0.4 mm max height

DIE SIZE BALL GRID ARRAY



#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.2. This drawing is subject to change without notice.

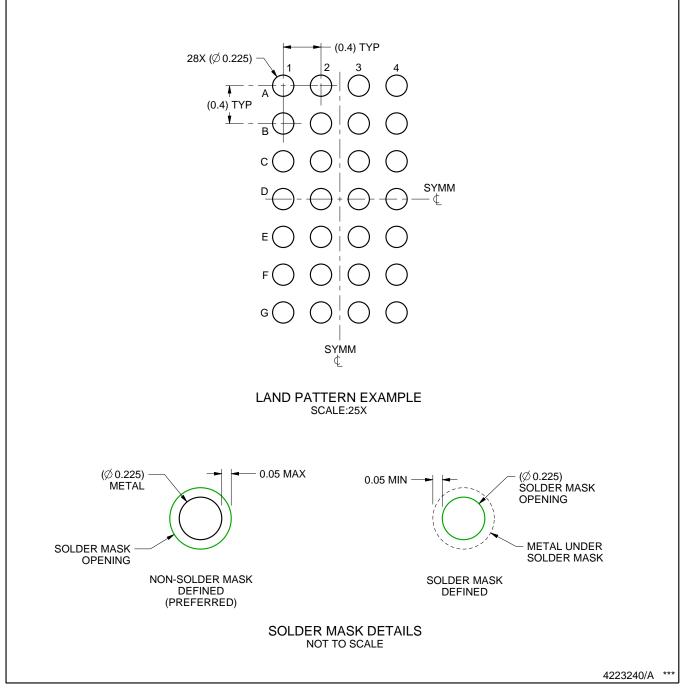


### YFD0028

# **EXAMPLE BOARD LAYOUT**

### DSBGA - 0.4 mm max height

DIE SIZE BALL GRID ARRAY



NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).

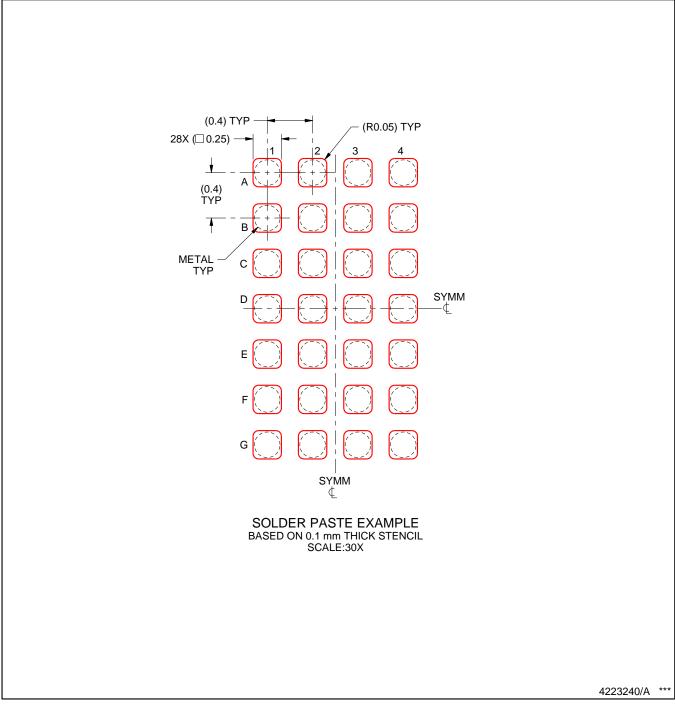


### YFD0028

# **EXAMPLE STENCIL DESIGN**

### DSBGA - 0.4 mm max height

DIE SIZE BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



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